AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-8. (Canceled)

9. (Currently amended) A method of mounting an electronic component in which a plurality of parts cassettes respectively accommodating different types of electronic components are moved by a component feeding unit to a component feeding position in a mounting order for feeding electronic components, and a plurality of component suction nozzles are successively moved along a circular track from a component pick-up position above the component feeding position, where the component suction nozzle picks up the electronic component, to a posture recognizing position, where the posture of the electronic component held with the component suction nozzle is detected, and further to a component mounting position, where the picked-up electronic component is mounted on [[the]] a circuit substrate, comprising:

obtaining data on an amount of displacement of the component from a prescribed holding position of the component suction nozzle corresponding to each

of the parts cassettes based on posture recognition results detected at the posture recognizing position; and

adjusting the component feeding position of a subsequently-fed electronic component to more accurately correspond to the component pick-up position based on said data on the amount of displacement.

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10. (Previously presented) The method of mounting an electronic component according to claim 9, wherein at least one of a position of the component feeding unit and a placing position of the parts cassettes onto the component feeding unit is adjusted based on said data on the amount of displacement.

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11. (Previously presented) The method of mounting an electronic component according to claim 9, wherein the component feeding position from each of the parts cassettes toward the component pick-up position is adjusted based on the displacement amount data.

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12. (Currently amended) A device for mounting an electronic component in which a plurality of parts cassettes respectively accommodating different types of electronic components are moved by a component feeding unit to a component feeding position in a mounting order for feeding electronic components, and a plurality of component suction nozzles are successively moved along a circular track

from a component pick-up position above the component feeding position, where the component suction nozzle picks up the electronic component, to a posture recognizing position, where the posture of the electronic component held with the component suction nozzle is detected, and further to a component mounting position, where the picked-up electronic component is mounted on [[the]] a circuit substrate, comprising:

displacement amount data processing means for obtaining data on an amount of displacement of the electronic component from a prescribed holding position of the suction nozzle corresponding to each of the parts cassettes based on posture recognition results detected at the posture recognizing position, and

drive means for moving at least one of the component feeding unit and the parts cassette in a direction to adjust the component feeding position to more accurately correspond to the component pick-up position for correcting the amount of displacement of the electronic component which is obtained from the displacement amount data for a subsequently-fed electronic component.

15. (Currently amended) A method of mounting an electronic component on a circuit substrate, comprising:

providing component suction nozzles successively movable along a circular travel path;

moving parts cassettes respectively accommodating different types of electronic components each to a component feeding position in a desired component mounting order such that a particular type of component of said electronic components can be picked-up by a particular component suction nozzle of said component suction nozzles which is located at a component pick-up position above said component feeding position;

picking up the particular type of electronic component from the component feeding position ~~component~~ by said particular component suction nozzle;

moving the particular type of electronic component to a posture recognizing position;

detecting a posture of the particular type of electronic component held by the particular component suction nozzle at the posture recognizing position;

~~further moving the particular type of electronic component to a component mounting position;~~

~~mounting the particular type of electronic component on the circuit substrate at said component mounting position;~~

obtaining data on an amount of displacement of the particular type of component from a prescribed holding position of the component suction nozzle corresponding to each of the parts cassettes based on posture recognition results detected at the posture recognizing position during said step of detecting; [[and]]

adjusting the component feeding position of a subsequently fed and picked-up electronic component to more accurately correspond to the component pick-up position based on said data on an amount of displacement;

moving the subsequently fed and picked-up electronic component to a component mounting position; and

mounting the subsequently fed and picked-up electronic component on the circuit substrate at said component mounting position.

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~~14.~~ (Previously presented) The method according to claim ~~13~~, further comprising storing the data on the amount of displacement of the particular type of component from the prescribed holding position of the component suction nozzle.

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~~15.~~ (Previously presented) The method according to claim ~~13~~, further comprising:

accommodating each of the different types of said electronic components in respective parts cassettes;

repeating said method for each of the different types of said electronic components; and

separately storing the data on the amount of displacement of the particular type of component measured each time the method is repeated.

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16. (Previously presented) The method according to claim 15, 7 further comprising determining whether a deviation between the component pick-up and the component feeding position for each of the different types of said electronic components, based upon said data on the amount of displacement, is limited to less than all types of said different types of electronic components.

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17. (Previously presented) The method according to claim 16, 8 wherein said step of adjusting includes individually adjusting a position of said parts cassettes when it is determined in said step of determining that less than all types of said different types of electronic components show said deviation.

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18. (Previously presented) The method according to claim 16, 8 wherein:

said step of moving parts cassettes includes operating a component feeding unit into which a group of the parts cassettes is loaded; and

said step of adjusting includes adjusting at least one of a position of the component feeding unit and a placing position of an entirety of the group of the parts cassettes onto the component feeding unit when it is determined in said step of determining that all types of said different types of electronic components show said deviation.

~~19.~~ 11 (Previously presented) The method according to claim ~~13,~~ 5 wherein said step of adjusting includes manual adjustment at a time when it is determined that said amount of displacement of the particular type of component is beyond a permissible range.

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~~20.~~ 12 (Previously presented) The method according to claim ~~13,~~ 5 wherein said step of adjusting includes operating a drive mechanism which implements said adjusting of the component feeding position.

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